

## ABSTRACT OF DISCLOSURE

A semiconductor device including: a semiconductor  
5 member having thereon a plurality of interconnect pads:  
and a mounting member having a plurality of electrode  
terminals electrically and mechanically connected to the  
respective interconnect pads for mounting the  
semiconductor chip on the mounting member, the  
10 electrode terminals forming a plurality of I/O cells each  
having part of the electrode terminals, the part of  
electrode terminals including signal terminals, the I/O  
cells forming a first group of the I/O cells and a second  
group of I/O cells disposed on an inner position of the  
15 mounting member with respect to the first group. The  
higher integration of the semiconductor device having the  
higher performances can be realized because the  
interconnect lines can be drawn to the outer periphery of  
the chip from the interconnect pads corresponding to each  
20 of the I/O cells when the chip is miniaturized or the  
number of the ball electrodes is increased.

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